

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Heonjoong KANG	07/02/2009
Jungwook CHIN	07/02/2009
Jaehwan LEE	07/02/2009
RECEIVING PARTY DATA	
Name:	Seoul National University Industry Foundation
Street Address:	San 4-2, Bongcheon-dong, Kwanak-gu
City:	Seoul
State/Country:	REPUBLIC OF KOREA
Postal Code:	151-742
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12517156
CORRESPONDENCE DATA	
Fax Number:	(860)286-0115
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	860-286-2929
Email:	jholmes@cantorcolburn.com
Correspondent Name:	CANTOR COLBURN, LLP
Address Line 1:	20 Church Street
Address Line 2:	22nd Floor
Address Line 4:	Hartford, CONNECTICUT 06103
ATTORNEY DOCKET NUMBER:	PLU-0049
NAME OF SUBMITTER:	James J. Merrick
Total Attachments: 2 source=2G76815#page1.tif	

OP \$40.00 12517156

501045432

PATENT
REEL: 023674 FRAME: 0449

ASSIGNMENT

WHEREAS We,

[KANG, Heonjoong]

of [412-305 Saetbyeolmaeul APT., Bundang-dong, Bundang-gu, Seongnam-si, Gyeonggi-do 463-749 Republic of Korea]

[CHIN, Jungwook]

of [A-738 Galleria palace, Jamsil 3-dong, Songpa-gu, Seoul 138-791 Republic of Korea]

[LEE, Jaehwan]

of [Basement #1, 244-16 Sillim 9-dong, Gwanak-gu, Seoul 151-859 Republic of Korea]

have invented certain new and useful improvements in:

ARYL COMPOUNDS AS PPAR LIGANDS AND THEIR USE


which claims priority to KR Application No. 10-2006-0121074, filed on 02 December 2006 and which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **SEOUL NATIONAL UNIVERSITY INDUSTRY FOUNDATION** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Republic of Korea, having a place of San 4-2, Bongcheon-dong, Kwanak-gu, Seoul 151-742, Republic of Korea, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

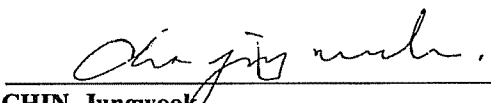
NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behalf of ASSIGNEE, its successors and assigns; and We do hereby agree that at the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 2 July, 2009


KANG, Heonjoong

Date: 2 July, 2009


CHIN, Jungwook

Date: 2 July, 2009

Lee Jaehwan
LEE, Jaehwan